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SIA USPAT Update

(FILE 'USPATFULL' ENTERED AT 15:41:28 ON 12 APR 2002)

DEL HIS
277 S (CMP OR POLISH? OR CHEMIMECH? OR PLANARIZ? OR LAP? OR GRIND?
L1 1509 S (CMP OR POLISH? OR CHEMIMECH? OR PLANARIZ? OR LAP? OR GRIND?
L2 1765 S L1 OR L2
L3 SET HIGH OFF
476 S L3 AND (SEMICONDUCT? OR WAFER# OR CHIP#)
L4 SET HIGH ON
476 S L3 AND L4
L5 116 S L1 AND L5
L6 33 S L6 AND (CMP OR POLISH? OR CHEMIMECH? OR PLANARIZ? OR LAP? OR
L7 83 S L6 NOT L7
L8 161 S L1 NOT (L7 OR L8)
L9 6 S L9 AND (CMP OR POLISH? OR CHEMIMECH? OR PLANARIZ? OR LAP? OR
L10 155 S L9 NOT L10
L11 SET HIGH OFF
365 S L2 AND (SEMICONDUCT? OR WAFER# OR CHIP#)
L12 SET HIGH ON
365 S L2 AND L12
L13 360 S L13 NOT L1
L14 SET HIGH OFF
2 S L14 AND MASS?(3A)SPEC?
L15 SET HIGH ON
2 S L14 AND L15
L16

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